

APPLICATION DATA SHEET

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Applicant Information:**Inventor 1:**

Applicant Authority Type:	Inventor
Citizenship:	DE
Given Name:	Hans
Family Name:	BELL
City of Residence:	Berlin
Country of Residence:	DE
Address-1 of Mailing Address:	Kreuzstrasse 18b
Address-2 of Mailing Address:	
City of Mailing Address:	Berlin
State of Mailing Address:	
Postal Code of Mailing Address:	13187
Country of Mailing Address:	DE
Phone:	
Fax:	
E-mail:	

Correspondence Information:

Customer Number:	26111	*26111*
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Application Information:

Title of Invention:	Method And Device For Reflow Soldering With Volume Flow Control
Application Type:	regular, utility
Attorney Docket Number:	2380.0030000

Botanic Information:

Publication Information:**Suggested Figure for Publication -****Suggested Classification -****Suggested Technology Center -****Total Number of Drawing Sheets - 3*****Representative Information:***

practitioner(s) at Customer Number:

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as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

Domestic Priority Information:

This is a National Stage of US application number PCT/EP2004/012262, filed 2004-10-29, now pending.

Foreign Priority Information:**Doc.No:**10350699.3; **Country** - DE; **Date:** 2003-10-30 us-priority-claimed***Assignee Information:***Assignee 1:**Organization Name:** Rehm Anlagenbau GmbH**Address-1 of Mailing Address:** Leinenstrasse 7**Address-2 of Mailing Address:****City of Mailing Address:** Blaubeuren-Seissen**State of Mailing Address:****Postal Code of Mailing Address:** 89143**Country of Mailing Address:** DE**Phone:****Fax:****E-mail:**

